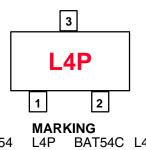


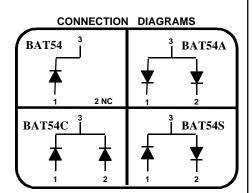
BAT54/A/C/S

PACKAGE

SOT-23 TO-236AB (Low)



BAT54 L4P BAT54C L43 BAT54A L42 BAT54S L44



Schottky Barrier Diode

Sourced from Process KA

Absolute Maximum Ratings* TA = 25°C unless otherwise noted

Sym	Parameter	Value	Units
T _{sta}	Storage Temperature	-55 to +150	оС
T _J	Operating Junction Temperature	+150	οС
W_{iv}	Working Inverse Voltage	25	V
I _E	DC Forward Current (IF)	200	mA
i _f	Recurrent Peak Forward Current (IFRM)	300	mA
i _{F(surge)}	Peak Forward Surge Current (IFSM) Pulse Width = 1.0 Second	600	mA
P _D	Total Power Dissipation at 25°C	230	mW
	Theta (Rth j-a) (Note 1)	430	°K/W

^{*}These ratings are limiting values above which the serviceability of any semiconductor device may be impaired

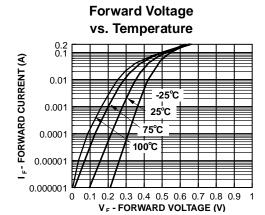
NOTES:

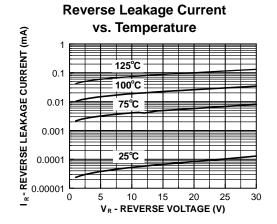
Electrical Characteristics TA = 25°C unless otherwise noted

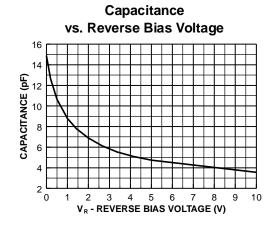
SYM	CHARACTERISTICS	MIN	MAX	UNITS	TEST CONDITIONS
B_V	Breakdown Voltage	30		V	$I_R = 10 \text{ uA}$
I _R	Reverse Leakage		2.0	uA	V _R = 25 V
V _F	Forward Voltage		240 320 400 500 1.0	mV mV mV V	$I_F = 100 \text{ uA}$ $I_F = 1.0 \text{ mA}$ $I_F = 10 \text{ mA}$ $I_F = 30 \text{ mA}$ $I_F = 100 \text{ mA}$
C _T	Capacitance		10	pF	V _R = 1.0 V f = 1.0 MHz
T _{RR}	Reverse Recovery Time		5.0	ns	$I_F = I_R = 10 \text{ mA}$ $I_{RR} = 1.0 \text{ mA}$ $R_L = 100 \text{ Ohms}$

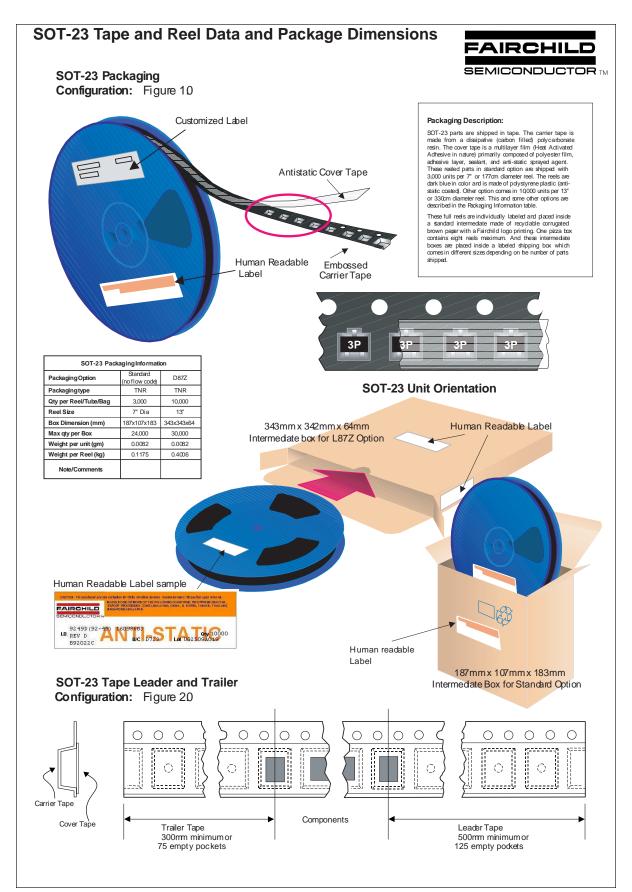
^{© 1997} Fairchild Semiconductor Corporation

¹⁾ From junction to ambient mounted on a ceramic substrate of 10 mm x 8 mm x 0.6 mm





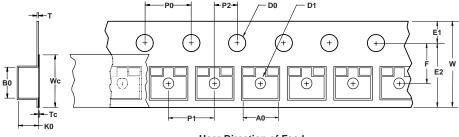




SOT-23 Tape and Reel Data and Package Dimensions, continued

SOT-23 Embossed Carrier Tape

Configuration: Figure 3.0



User Direction of Feed

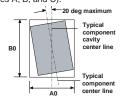
Dimensions are in millimeter														
Pkg type	Α0	В0	w	D0	D1	E1	E2	F	P1	P0	K0	т	Wc	Тс
SOT-23 (8mm)	3.15 +/-0.10	2.77 +/-0.10	8.0 +/-0.3	1.55 +/-0.05	1.125 +/-0.125	1.75 +/-0.10	6.25 min	3.50 +/-0.05	4.0 +/-0.1	4.0 +/-0.1	1.30 +/-0.10	0.228 +/-0.013	5.2 +/-0.3	0.06 +/-0.02

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



Sketch A (Side or Front Sectional View)

Component Rotation



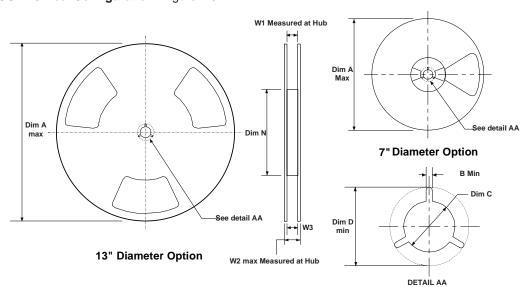
Sketch B (Top View)
Component Rotation



Sketch C (Top View)

Component lateral movement

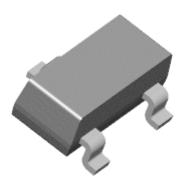
SOT-23 Reel Configuration: Figure 4.0

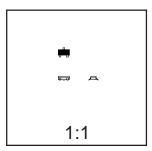


Dimensions are in inches and millimeters									
Tape Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2	Dim W3 (LSL-USL)
8mm	7" Dia	7.00 177.8	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	2.165 55	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9
8mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	4.00 100	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9

SOT-23 Tape and Reel Data and Package Dimensions, continued

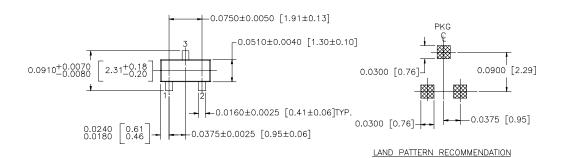
SOT-23 (FS PKG Code 49)

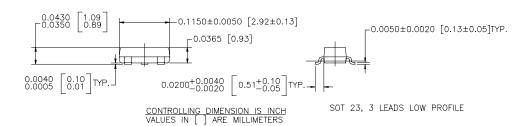




Scale 1:1 on letter size paper Dimensions shown below are in: inches [millimeters]

Part Weight per unit (gram): 0.0082





NOTE: UNLESS OTHERWISE SPECIFIED

- 1. STANDARD LEAD FINISH 150 MICROINCHES / 3.81 MICROMETERS MINIMUM TIN / LEAD (SOLDER) ON ALLOY 42
- 2. REFERENCE JEDEC REGISTRATION TO-236, VARIATION AB, ISSUE G, DATED JUL 1993

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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.				
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.				